

Excellent Integrated System Limited

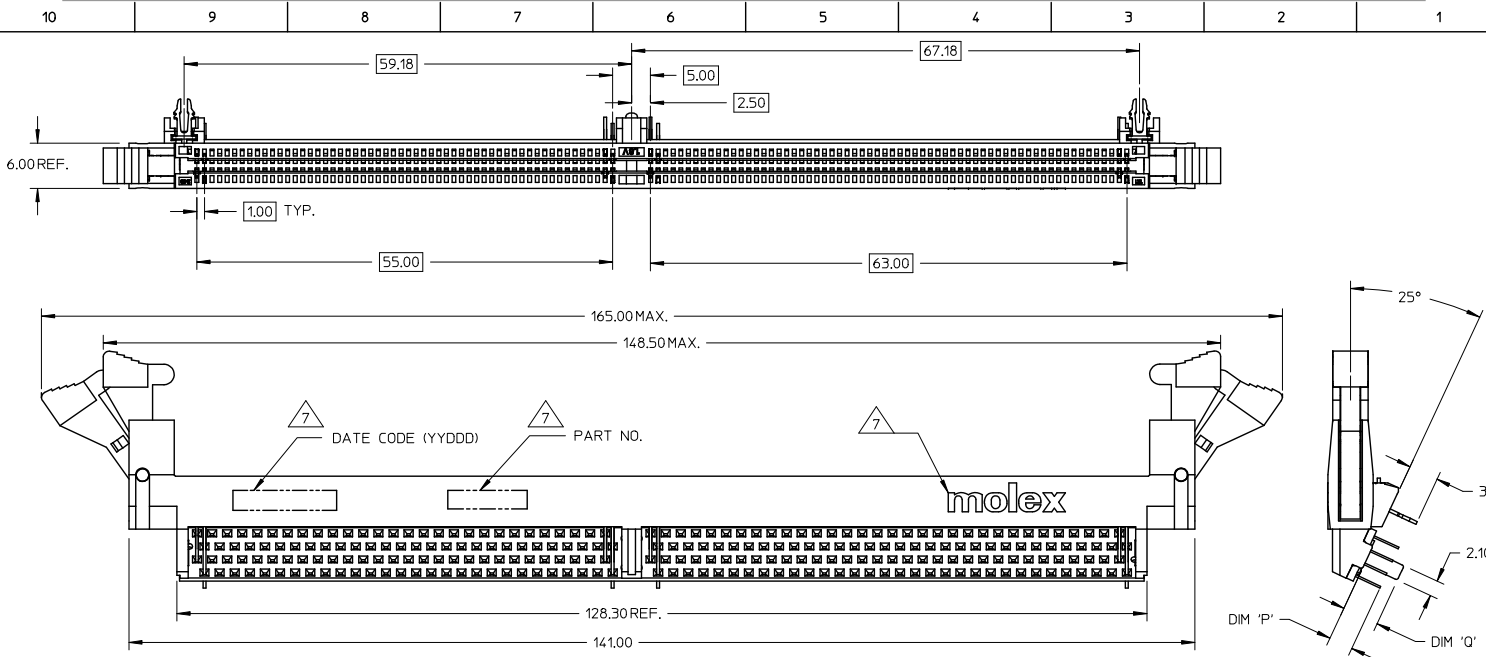
Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[87803-0002](#)

For any questions, you can email us directly:

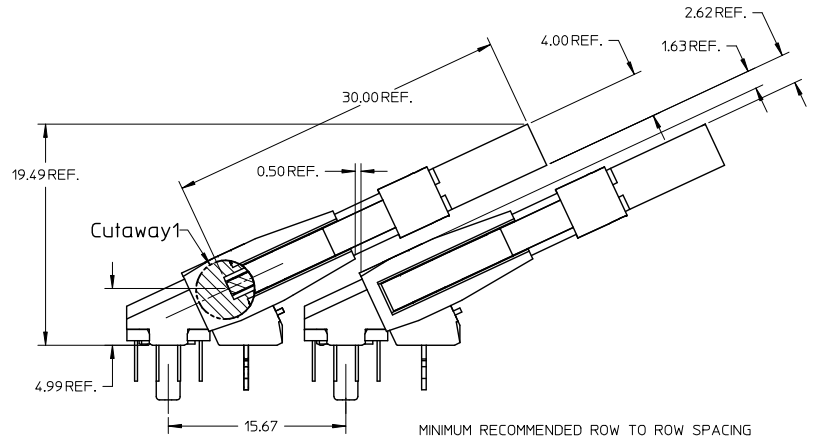
sales@integrated-circuit.com



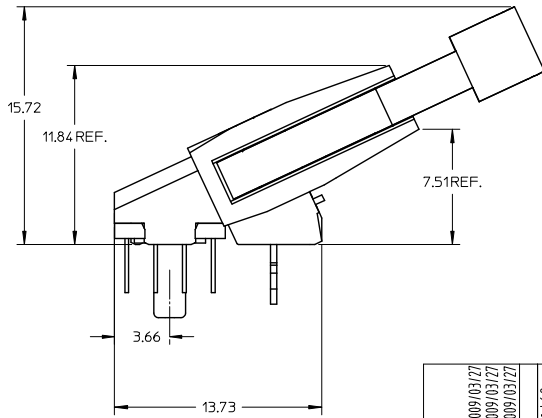
- NOTES:
1. MATERIALS : HOUSING AND BASEPLATE
- LCP, GLASS FILLED, UL 94V-0, BLACK LATCH
- HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)
TERMINALS AND FORKLICK - COPPER ALLOY
 2. PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
SOLDERTAIL - SEE TABLE IN SHEET 5
 3. REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
 4. CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
 5. RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
 6. PRODUCT IS PACKED IN TRAY.
 7. MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
 8. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

ADDED OPTION EC NO. S2009-0629 DRAWN: CTEH CHKD: CGTAN APPR: SHLENI 2009/03/27 2009/03/27 2009/03/27	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	DRAWN BY MLONG	DATE 2004/03/25	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
		ANGULAR ± 5 °				CHECKED BY SRRAMESH	DATE 2004/03/26	MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				APPROVED BY GGLEE	DATE 2004/03/26	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87803-010	SHEET NO. 1 OF 5

10 9 8 7 6 5 4 3 2 1

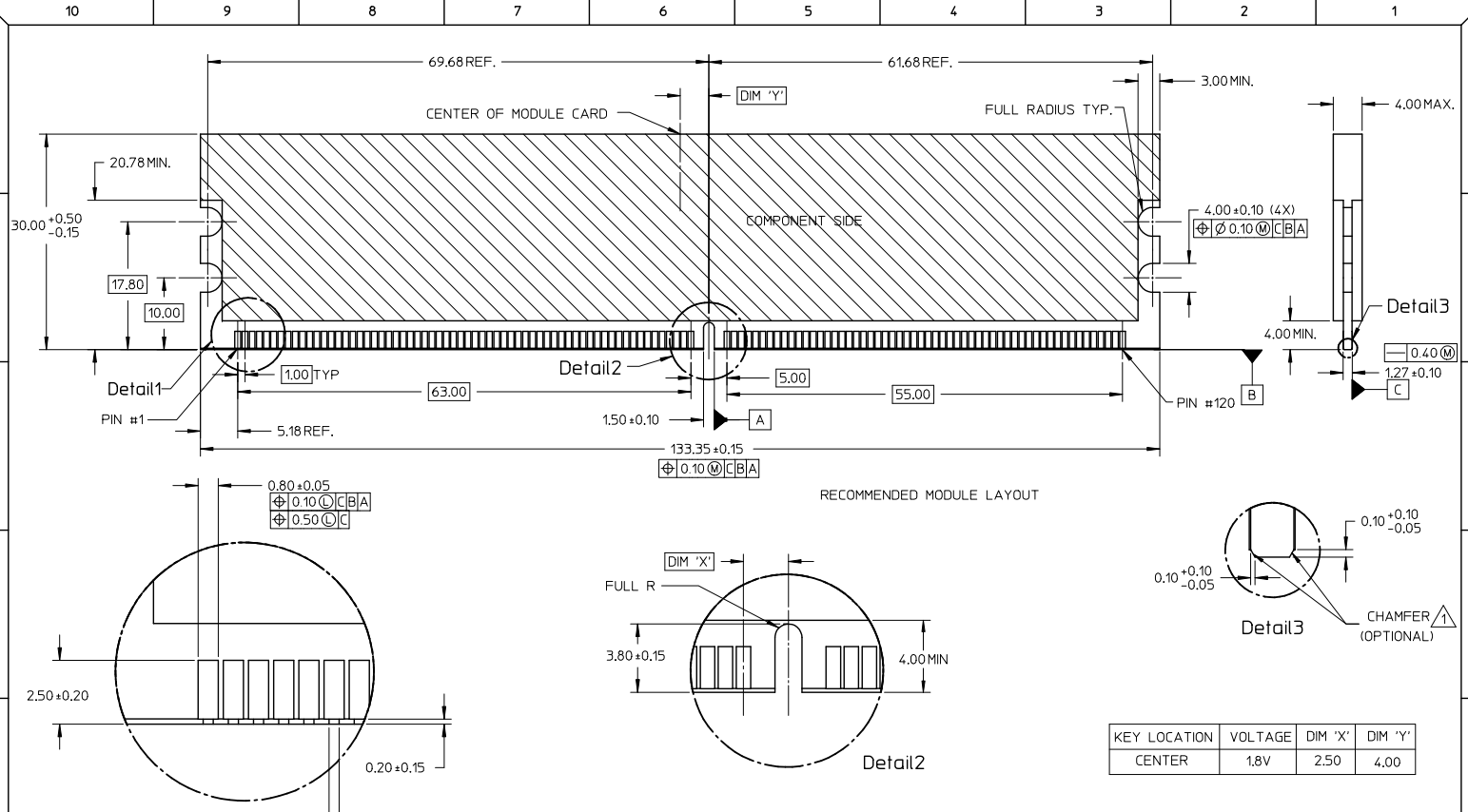


MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00MM THICK
MODULE (TYPICAL TSOP PACKAGING)



ADDED OPTION EC NO: S2009-0629 2009/03/27 DRAWN: CTEH 2009/03/27 CHKD: LGTAN 2009/03/27 APPR: SHLENI 2009/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	▼=0 ▽=0	4 PLACES ±---	±---	DRAWN BY MLONG	DATE 2004/03/25	TITLE	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
		3 PLACES ±---	±---	CHECKED BY SRRAMESH	DATE 2004/03/26	MOLEX INCORPORATED DOCUMENT NO. SD-87803-010 SHEET NO. 2 OF 5			
		2 PLACES ±0.25	±---	APPROVED BY GGLEE	DATE 2004/03/26				
	1 PLACE ±---	±---	ANGULAR ± 5°		MATERIAL NO. SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

9 8 7 6 5 4 3 2 1

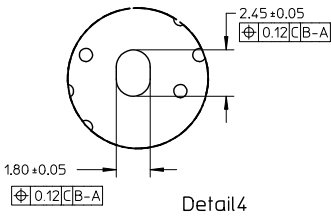
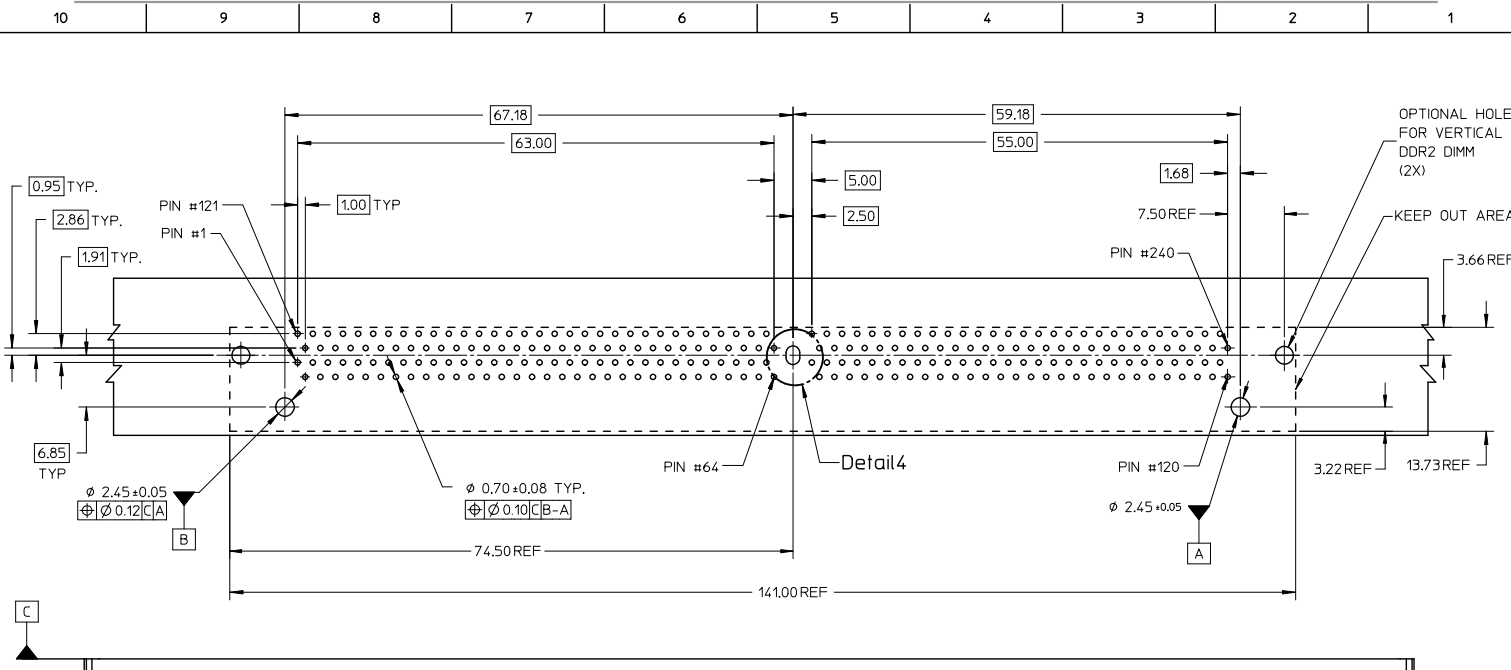


KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

Detail1
TIE BAR KEEP OUT ZONE

NOTES :
△ MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.

ADDED OPTION EC NO. S2009-0629 DRAWN/CHEK 2009/03/27 CHKD/CGTAN 2009/03/27 APPR/SILENI 2009/03/27	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH	DRAWN BY	DATE			
B1	REV	4 PLACES	± ---	± ---	MLONG	2004/03/25	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.	MATERIAL NO. SEE TABLE
		3 PLACES	± ---	± ---	CHECKED BY	DATE		
		2 PLACES	± 0.25	± ---	SRRAMESH	2004/03/26		
		1 PLACE	± ---	± ---	APPROVED BY	DATE		
		ANGULAR ± 5 °		GGLLEE		2004/03/26	MOLEX INCORPORATED	DOCUMENT NO. SD-87803-010
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 3 OF 5



ADDED OPTION EC NO: S2009-0629 DRAWN: CTEH CHYKD: LGTAN APPR: SHLENI 2009/03/27 2009/03/27 2009/03/27	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DIMENSION STYLE MM ONLY DRAWN BY MLONG DATE 2004/03/25 CHECKED BY SRRAMESH DATE 2004/03/26 APPROVED BY GGLEE DATE 2004/03/26	SCALE NTS DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.	
	MATERIAL NO. SEE TABLE DOCUMENT NO. SD-87803-010	SHEET NO. 4 OF 5	MOLEX INCORPORATED			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBRICATION
87803-0002	1.8V	2.79	3.18	1.57	0.38uM/ 15u" GOLD OVER 1.27uM/ 50u" MIN NICKEL	2.54uM/ 100u" MIN. TIN (MATTE) OVER 1.27uM/ 50u" MIN NICKEL	NO
87803-0022							YES
87803-0012							NO
87803-0032		YES					
87803-0052		NO					
87803-0062		YES					
87803-0102		2.79	3.18	1.57	0.76uM/ 30u" GOLD OVER 1.27uM/ 50u" MIN NICKEL		NO
87803-0122							YES
87803-0112							NO
87803-0132		YES					
87803-0152		NO					
87803-0162		YES					

ADDED OPTION EC. NO. S2009-0629 DRAWN/CTEH 2009/03/27 CHKD:CGTAN 2009/03/27 APPR: SILENI 2009/03/27 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$ $\nabla=0$	mm INCH	MM ONLY	NTS	METRIC	
	4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DRAWN BY DATE MLONG 2004/03/25 CHECKED BY DATE SRRAMESH 2004/03/26 APPROVED BY DATE GGLEE 2004/03/26	TITLE	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE SIZE A3	MOLEX INCORPORATED DOCUMENT NO. SD-87803-010 SHEET NO. 5 OF 5	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1